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Title: A Bonded Wafer Processing Method
Inventor: Morrow et al.
Filing Date: Concurrently Herewith
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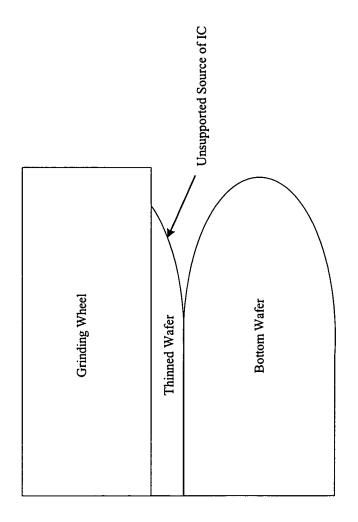
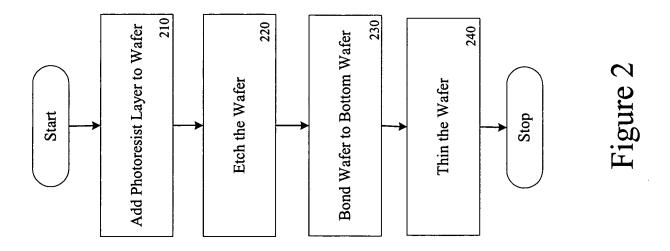


Figure 1 (PRIOR ART)

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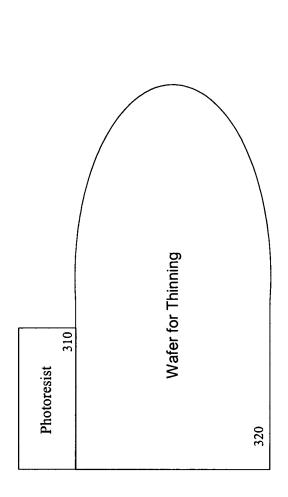
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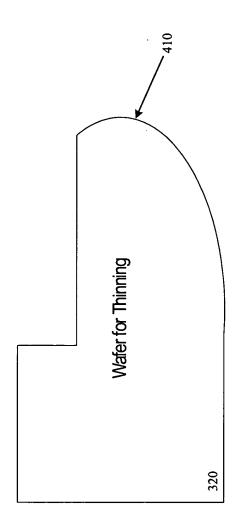


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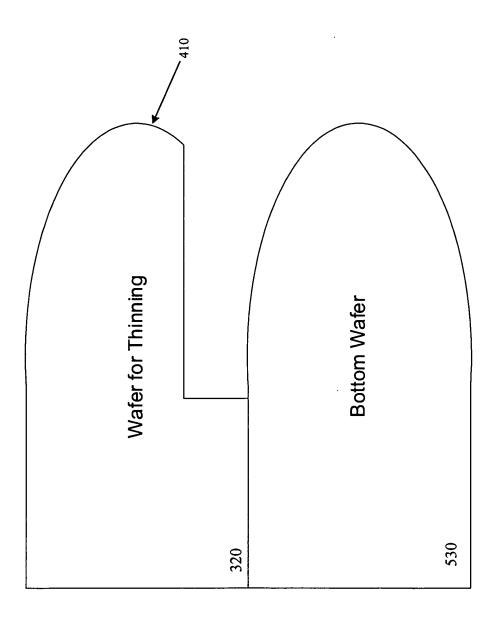


Figure 5

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Grinding Wheel Bottom Wafer 320 Wafer for Thinning